

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An apparatus for etching a glass substrate, comprising:  
an etching bath containing an etchant;  
a holder for supporting said glass substrate in the etching bath;  
an ultrasonic oscillator generating ultrasonic vibration on opposite surfaces of said substrate; and

wherein the ultrasonic oscillator is located in the interior of the etching bath and the ultrasonic oscillator completely surrounds the bottom and sides of the etching bath. ~~on two opposite sides of the etching bath; and~~  
~~an indicator displaying a temperature of the etching bath.~~

2. (Original) The apparatus for etching a glass substrate of Claim 1, wherein said etchant comprises hydrofluoric acid.

3. (Original) The apparatus for etching a glass substrate of Claim 1, wherein said holder comprises acid-resistant material.

4. (Original) The apparatus for etching a glass substrate of Claim 3, wherein said acid resistant material comprises polytetrafluoroethylene.

5. (Original) The apparatus for etching a glass substrate of Claim 1, further comprising a thermometer for measuring the temperature of the etchant.

6. (Original) The apparatus for etching a glass substrate of Claim 1, further comprising a thermostat for signaling a specific temperature rise of said etchant.

7. (Original) The apparatus for etching a glass substrate of Claim 1, wherein said holder supports a plurality of glass substrates.

Claims 8 and 9 (Canceled).

10. (Original) The apparatus for etching a glass substrate of Claim 1, wherein said holder is located in an interior of said etching bath.

11. (Currently Amended) An apparatus for etching a glass substrate, comprising:  
an etching bath filled with an etchant;  
a holder for supporting said glass substrate in the etching bath;  
an ultrasonic oscillator generating ultrasonic vibration on opposite surfaces of said substrate, ~~wherein the ultrasonic vibration emanates from bottom and side surfaces of the etching bath and~~ wherein the ultrasonic oscillator is located in the interior of the etching bath and the ultrasonic oscillator completely surrounds the bottom and sides of the etching bath; and  
an indicator displaying a temperature of the etching bath.

12. (Previously Presented) The apparatus for etching a glass substrate of Claim 21, further comprising a control unit for receiving a temperature indicating signal from said temperature sensor and generating an etching termination signal when the temperature signal indicates an etching termination temperature.

13. (Original) The apparatus for etching a glass substrate of Claim 12, wherein said control unit determines said etching termination temperature from said temperature indicating signal.

14. (Original) The apparatus for etching a glass substrate of Claim 11, wherein said etchant comprises hydrofluoric acid.

15. (Original) The apparatus for etching a glass substrate of Claim 11, wherein said holder comprises acid resistant material.

16. (Original) The apparatus for etching a glass substrate of Claim 15, wherein said acid resistant material comprises polytetrafluoroethylene.

17. (Original) The apparatus for etching a glass substrate of Claim 11, wherein said holder contains a plurality of glass substrates.

Claims 18 and 19 (Canceled).

20. (Original) The apparatus for etching a glass substrate of Claim 11, wherein said holder is located in an interior of said etching bath.

21. (Previously Presented) The apparatus for etching a glass substrate of Claim 11, further comprising a temperature sensor installed in said etching bath, wherein the temperature sensor monitors the temperature of the etching bath.